### EC4SMA-25.000M

Vibration





Series 4.0mm Epoxy Base SMD Crystal

Frequency Tolerance/Stability ±50ppm at 25°C, ±100ppm over -20°C to +70°C

Mode of Operation AT-Cut Fundamental

#### -25.000M

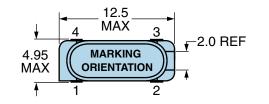
L Nominal Frequency 25.000MHz

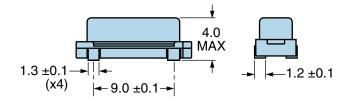
Load Capacitance 18pF Parallel Resonant

ELECTRICAL SPECIFICATIONS			
Nominal Frequency	25.000MHz		
Frequency Tolerance/Stability	±50ppm at 25°C, ±100ppm over -20°C to +70°C		
Aging at 25°C	±5ppm/year Maximum		
Load Capacitance	18pF Parallel Resonant		
Shunt Capacitance (C0)	7pF Maximum		
Equivalent Series Resistance	40 Ohms Maximum		
Mode of Operation	AT-Cut Fundamental		
Drive Level	1mWatts Maximum		
Storage Temperature Range	-40°C to +85°C		
Insulation Resistance	500 Megaohms Minimum at 100Vdc		
ENVIRONMENTAL & MECHANICAL SPECIFICATIONS			
Fine Leak Test	MIL-STD-883, Method 1014 Condition A		
Gross Leak Test	MIL-STD-883, Method 1014 Condition C		
Mechanical Shock	MIL-STD-202, Method 213 Condition C		
Resistance to Soldering Heat	MIL-STD-202, Method 210		
Resistance to Solvents	MIL-STD-202, Method 215		
Solderability	MIL-STD-883, Method 2003		
Temperature Cycling	MIL-STD-883, Method 1010		

### **MECHANICAL DIMENSIONS (all dimensions in millimeters)**

MIL-STD-883, Method 2007 Condition A





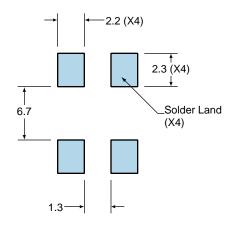
PIN	CONNECTION
1	Connected to Pin 4 and to Crystal
2	Connected to Pin 3 and to Crystal
3	Connected to Pin 2 and to Crystal
4	Connected to Pin 1 and to Crystal
LINE	MARKING
1	<b>E25.000</b> <i>E=Ecliptek Designator</i>

# EC4SMA-25.000M



### Suggested Solder Pad Layout

All Dimensions in Millimeters

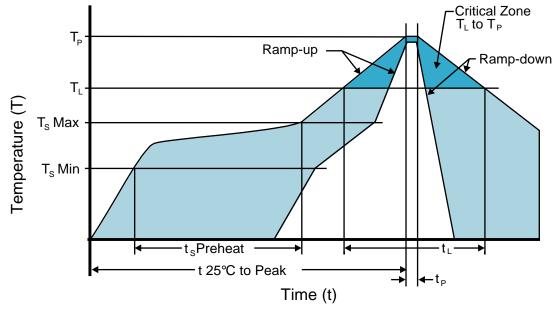


All Tolerances are ±0.1

# EC4SMA-25.000M



### **Recommended Solder Reflow Methods**



### Low Temperature Infrared/Convection 225°C

T <sub>s</sub> MAX to T <sub>L</sub> (Ramp-up Rate)	5°C/second Maximum
Preheat	
- Temperature Minimum (T <sub>s</sub> MIN)	N/A
- Temperature Typical (T <sub>s</sub> TYP)	150°C
- Temperature Maximum (T <sub>s</sub> MAX)	N/A
- Time (t <sub>s</sub> MIN)	30 - 60 Seconds
Ramp-up Rate (T⊾ to T <sub>P</sub> )	5°C/second Maximum
Time Maintained Above:	
- Temperature (T∟)	150°C
- Time (t∟)	200 Seconds Maximum
Peak Temperature (T <sub>P</sub> )	225°C Maximum
Target Peak Temperature (T <sub>P</sub> Target)	225°C Maximum 2 Times
Time within 5°C of actual peak (t <sub>p</sub> )	80 seconds Maximum 2 Times
Ramp-down Rate	5°C/second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

#### Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

### **High Temperature Manual Soldering**

260°C Maximum for 5 seconds Maximum, 2 times Maximum.